

Features

• -30V/-30A,

 $R_{DS (ON)} = 10 \text{m}\Omega(\text{Typ.})@V_{GS} = -10 \text{V}$

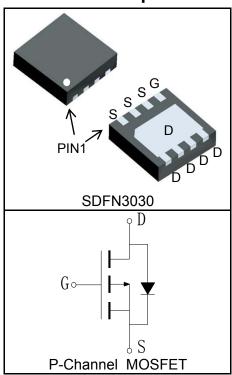
 $R_{DS (ON)} = 18 m\Omega (Typ.) @V_{GS} = -4.5 V$

- Super High Dense Cell Design
- Reliable and Rugged
- 100% Avalanche Tested
- Lead Free and Green Devices Available (RoHS Compliant)

Applications

- Power Management
- Load Switching

Pin Description



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit				
Common Ratings (T _C =25°C Unless Otherwise Noted)							
V _{DSS}	Drain-Source Voltage			V			
V _{GSS}	Gate-Source Voltage		±20	V			
T _J	Maximum Junction Temperature		150	°C			
T _{STG}	Storage Temperature Range			°C			
I _S	Diode Continuous Forward Current	-30	Α				
Mounted on Large Heat Sink							
I _{DP}	300µs Pulse Drain Current Tested	T _C =25°C	-96	Α			
	Continuous Proin Current®T (V = 10V)	T _C =25°C	-30	А			
I _D ^②	Continuous Drain Current@T _C (V _{GS} =-10V)	T _C =100°C	-19				
		T _A =25°C	-9.3				
	Continuous Drain Current@T _A (V _{GS} =-10V) ³	T _A =70°C	-7.5				
P_{D}	Maximum Bower Dissination @T	T _C =25°C	33				
	Maximum Power Dissipation@T _C	T _C =100°C	13	W			
		T _A =25°C	3.5	VV			
	Maximum Power Dissipation@ $T_A^{(3)}$ $T_A=70^{\circ}$		2.3				



Symbol	Parameter	Rating	Unit			
$R_{ heta JC}$	Thermal Resistance-Junction to Case	3.8	°C/W			
$R_{ heta JA}^{\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $	Thermal Resistance-Junction to Ambient	35	°C/W			
Drain-Source Avalanche Ratings						
E _{AS}	Avalanche Energy, Single Pulsed		mJ			

Electrical Characteristics (T_C=25°C Unless Otherwise Noted)

Cymals al	Dorometer	Took Condition	RU30L30M3			11:4:4	
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit	
Static Cha	racteristics		•				
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-30			V	
	Zoro Cato Valtago Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μΑ	
I _{DSS}	Zero Gate Voltage Drain Current	T _J =125°C			-30		
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=-250\mu A$	-1		-2.5	V	
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V			±10	μа	
5	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-20A		10	12	mΩ	
R _{DS(ON)}	Dialii-Source Off-State Resistance	V _{GS} =-4.5V, I _{DS} =-16A		18	20	mΩ	
Diode Cha	racteristics						
V _{SD} ^⑤	Diode Forward Voltage	I _{SD} =-20A, V _{GS} =0V			-1.5	V	
trr	Reverse Recovery Time	I 20 A di/dt-400 A/vo		45		ns	
Qrr	Reverse Recovery Charge	Isp=-20A, dlsp/dt=100A/μs		26		nC	
Dynamic C	Characteristics [©]						
R_{G}	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz		1.8		Ω	
C _{iss}	Input Capacitance	V _{GS} =0V,		2300			
C _{oss}	Output Capacitance	V _{DS} =-15V, Frequency=1.0MHz		250		pF	
C _{rss}	Reverse Transfer Capacitance	Trequency—1.0mm2		160			
t _{d(ON)}	Turn-on Delay Time			17			
t _r	Turn-on Rise Time	V _{DD} =-15V,I _{DS} =-20A,		32		ns	
t _{d(OFF)}	Turn-off Delay Time	V_{GEN} =-10V, R_{G} =6 Ω		37			
t _f	Turn-off Fall Time			15			
Gate Char	ge Characteristics [®]						
Q_g	Total Gate Charge			42		nC	
Q_{gs}	Gate-Source Charge	V _{DS} =-24V, V _{GS} =-10V, I _{DS} =-20A		9			
Q_{gd}	Gate-Drain Charge	יטס בטיי		13			



Notes:

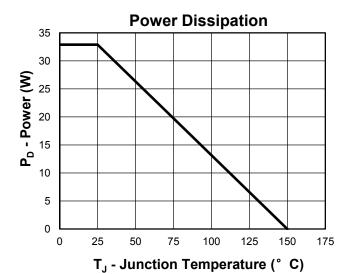
- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, t≤10sec.
- 4Limited by T_{Jmax}, I_{AS}=-12A,V_{DD}=-24V,R_G=50Ω,Starting T_J = 25°C.
- ⑤Pulse test;Pulse width≤300μs, duty cycle≤2%.
- **©**Guaranteed by design, not subject to production testing.

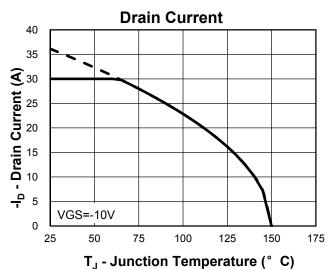
Ordering and Marking Information

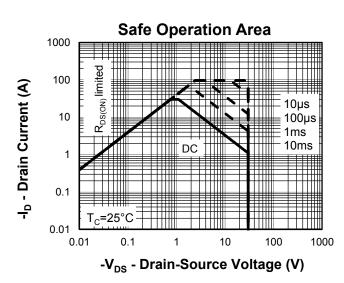
Device	Marking	Package	Packaging	Quantity	Reel Size	Tape width
RU30L30M3	30L30	SDFN3030	Tape&Reel	3000	7"	8mm

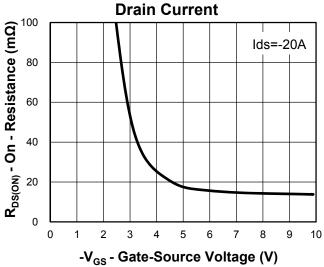


Typical Characteristics

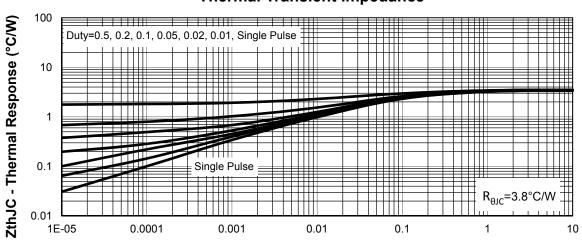








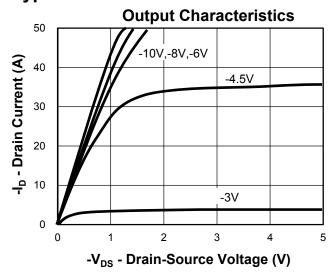
Thermal Transient Impedance

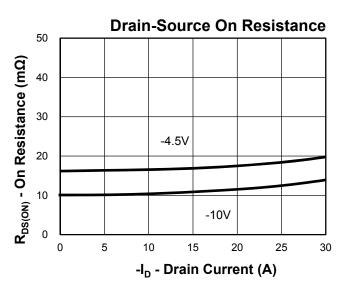


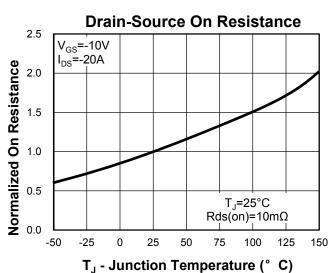
Square Wave Pulse Duration (sec)

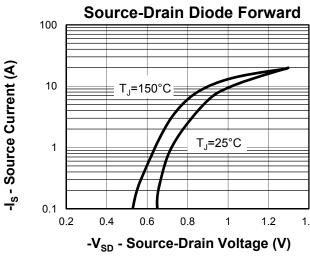


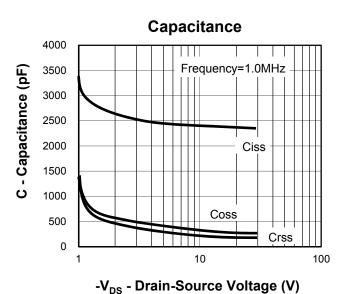
Typical Characteristics

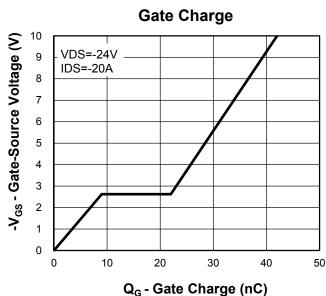






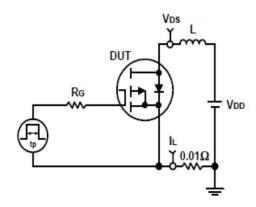


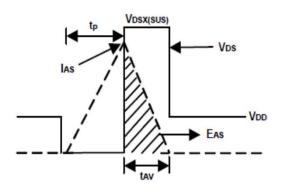




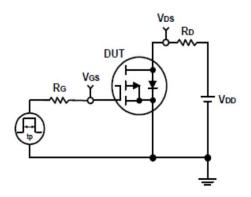


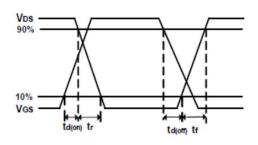
Avalanche Test Circuit and Waveforms





Switching Time Test Circuit and Waveforms



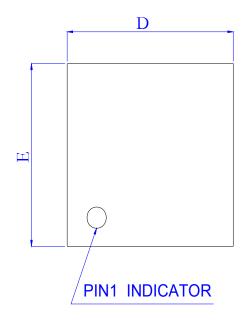


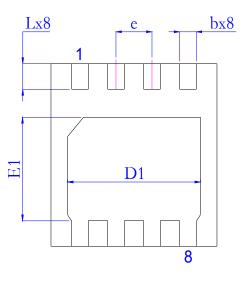
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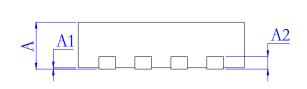


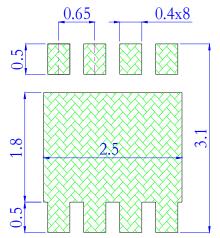
Package Information

SDFN3030









Land Pattern (Only for Reference)

SYMBOL	MM			INCH			
	MIN	NOM	MAX	MIN	NOM	MAX	
A	0.700	0.750	0.800	0.028	0.030	0.031	
A1	0.000	0.020	0.050	0.000	0.001	0.002	
A2	0. 203 REF.			0.008 REF.			
b	0.250	0.300	0.350	0.010	0.012	0.014	
D	2.900	3.000	3. 100	0.114	0.118	0. 122	
D1	2.350	2.400	2. 450	0.093	0.094	0.096	
Е	2.900	3.000	3. 100	0.114	0.118	0. 122	
E1	1.650	1.700	1.750	0.065	0.067	0.069	
е	0.650BSC			0. 026BSC			
L	0.370	0.420	0.470	0.015	0.017	0.019	



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